

PATENT ABSTRACTS OF JAPAN

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(54) RESIN MOLD TYPE SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To obtain a suitable device which serves for large-output one with radiation improved by arranging a thermal conductor for radiation on the reverse surface of the tab of a lead, constituting the resin mold type semiconductor device, through a thermally conductive connecting material. CONSTITUTION: Semiconductor pellet 4, fixed onto tab 1 of the lead frame through conductive connecting material 3, is connected to lead 2 by using connector wire 5. Next, thermal conductor 7 is adhered onto the reverse surface of tab 1 through thermally conductive connecting material 6 and the whole is sealed by resin with the reverse surface exposed. Then, radiation conductor 7 constituted previously is arranged on the lamination body of glass epoxy wiring substrate 12 and ceramic wiring substrate 8 provided onto chassis 20, with the reverse surface of conductor 7 made in contact, and pressed down by package weight 21 via spring 22. As a result, the radiation path from tab 1 is shortened and the radiation area can be widened, so that radiation effects will improve remarkably.

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